

SOT846-1

plastic thermal enhanced ball grid array package; 760 balls;
body 40 x 40 x 1.75 mm; heatsink

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	HBGA760
Package type industry code	HBGA760
Package style descriptive code	HBGA (thermal enhanced ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MS-034
Mounting method type	S (surface mount)
Issue date	19-8-2005

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		39.8	-	40	40.2	mm
E	package width		39.8	-	40	40.2	mm
A	seated height		[tbd]	-	2.55	2.55	mm
A ₂	package height		1.6	-	1.75	1.85	mm
n ₂	actual quantity of termination		-	-	760	-	



2. Package outline

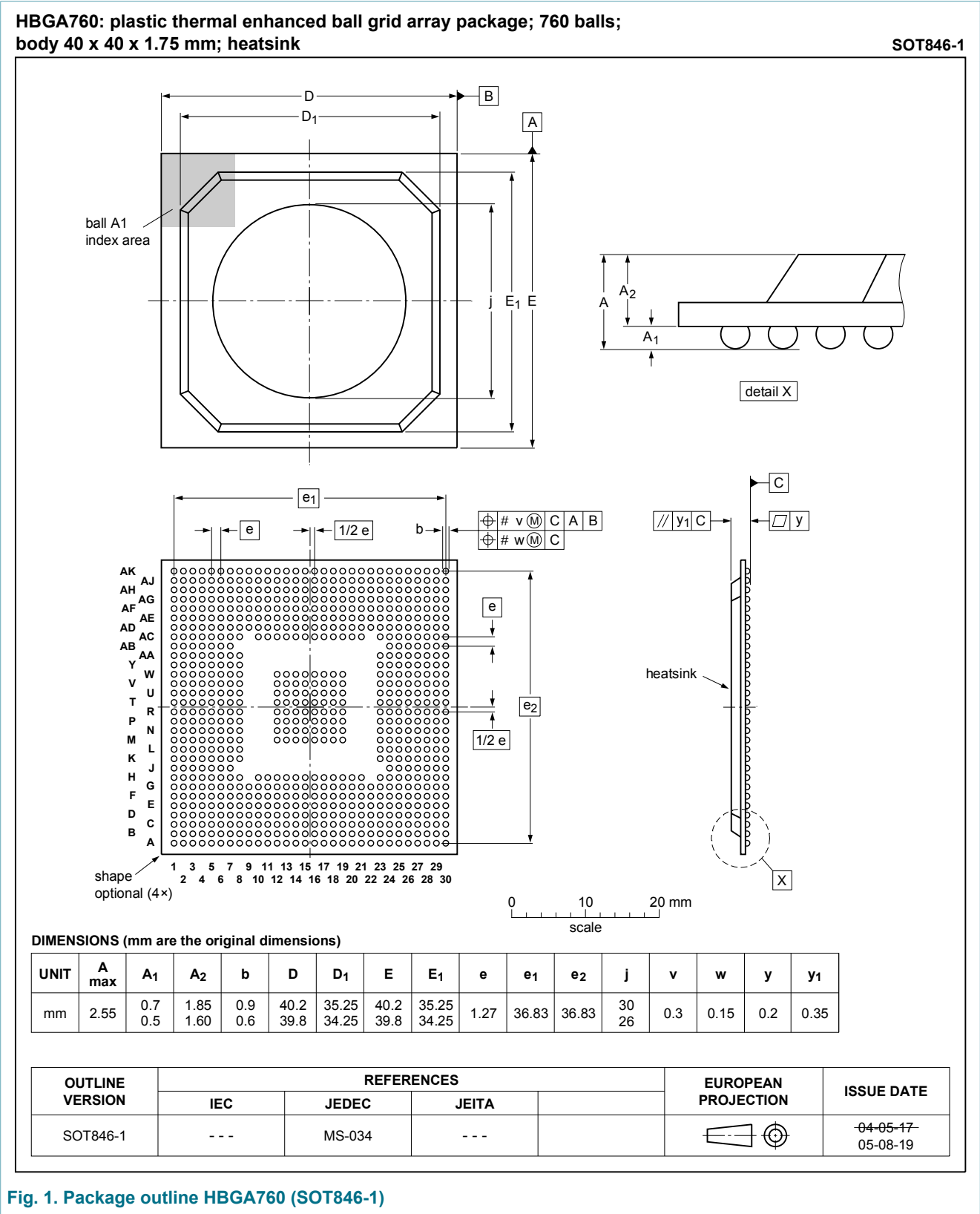


Fig. 1. Package outline HBGA760 (SOT846-1)

3. Soldering

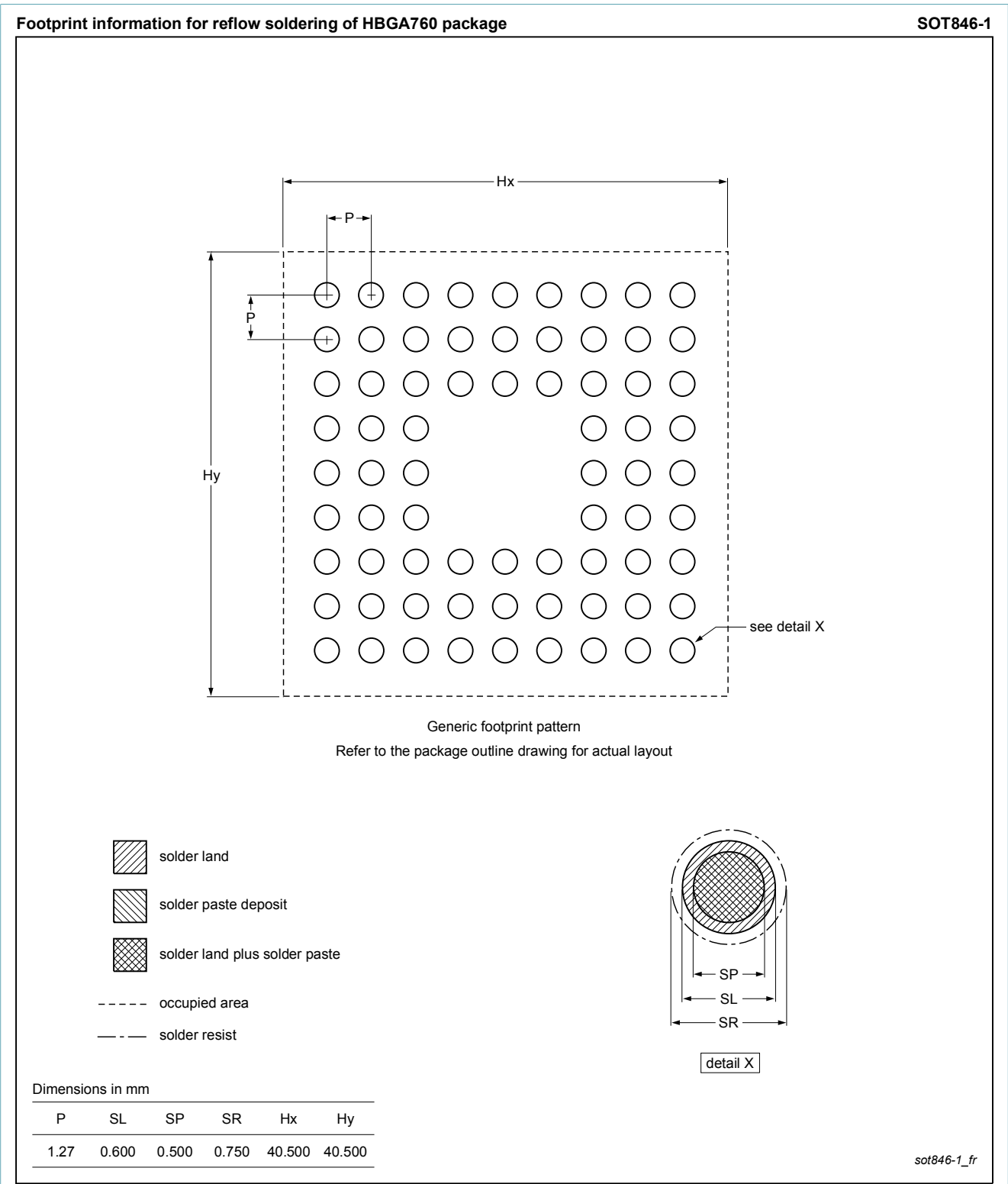


Fig. 2. Reflow soldering footprint for HBGA760 (SOT846-1)

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4. Legal information

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